

**Insulated Gate Bipolar Transistor**
**General Description:**

Using DongHai's proprietary Planar design and advanced FS technology, the 650V FS IGBT offers superior conduction and switching performances, high avalanche ruggedness and easy parallel operation.

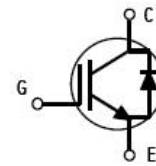
**Features:**

- FS Trench Technology, Positive temperature coefficient
- Low saturation voltage:  $V_{CE(sat)}$ , typ = 1.85V @  $I_C = 60A$  and  $T_C = 25^\circ C$
- Extremely enhanced avalanche capability

**Applications:**

Aircondition、Welding、UPS...

$V_{CES}$	<b>650</b>	<b>V</b>
$I_C$	<b>60</b>	<b>A</b>
$P_{tot}$ ( $T_C=25^\circ C$ )	<b>406</b>	<b>W</b>
$V_{CE(sat)}$	<b>1.85</b>	<b>V</b>

**TO-247 PACKAGE**

**Absolute Maximum Ratings (  $T_C = 25^\circ C$  unless otherwise specified ) :**

Symbol	Parameter	Rating	Units
$V_{CES}$	Collector-Emitter Voltage	650	V
$V_{GES}$	Gate- Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current	120	A
	Collector Current @ $T_C = 100^\circ C$	60	
$I_{CM}^{a1}$	Pulsed Collector Current	180	A
$I_F$	Diode Continuous Forward Current @ $T_C = 100^\circ C$	30	A
$I_{FM}$	Diode Maximum Forward Current	90	A
$P_D$	Power Dissipation @ $T_C = 25^\circ C$	406	W
	Power Dissipation @ $T_C = 100^\circ C$	163	
$T_J$	operating junction temperature range	150	$^\circ C$
$T_{stg}$	Storage Temperature Range	$-55 \sim 150$	$^\circ C$
$T_L$	Maximum Temperature for Soldering	270	$^\circ C$

a1: The pulse width is limited by the maximum junction temperature

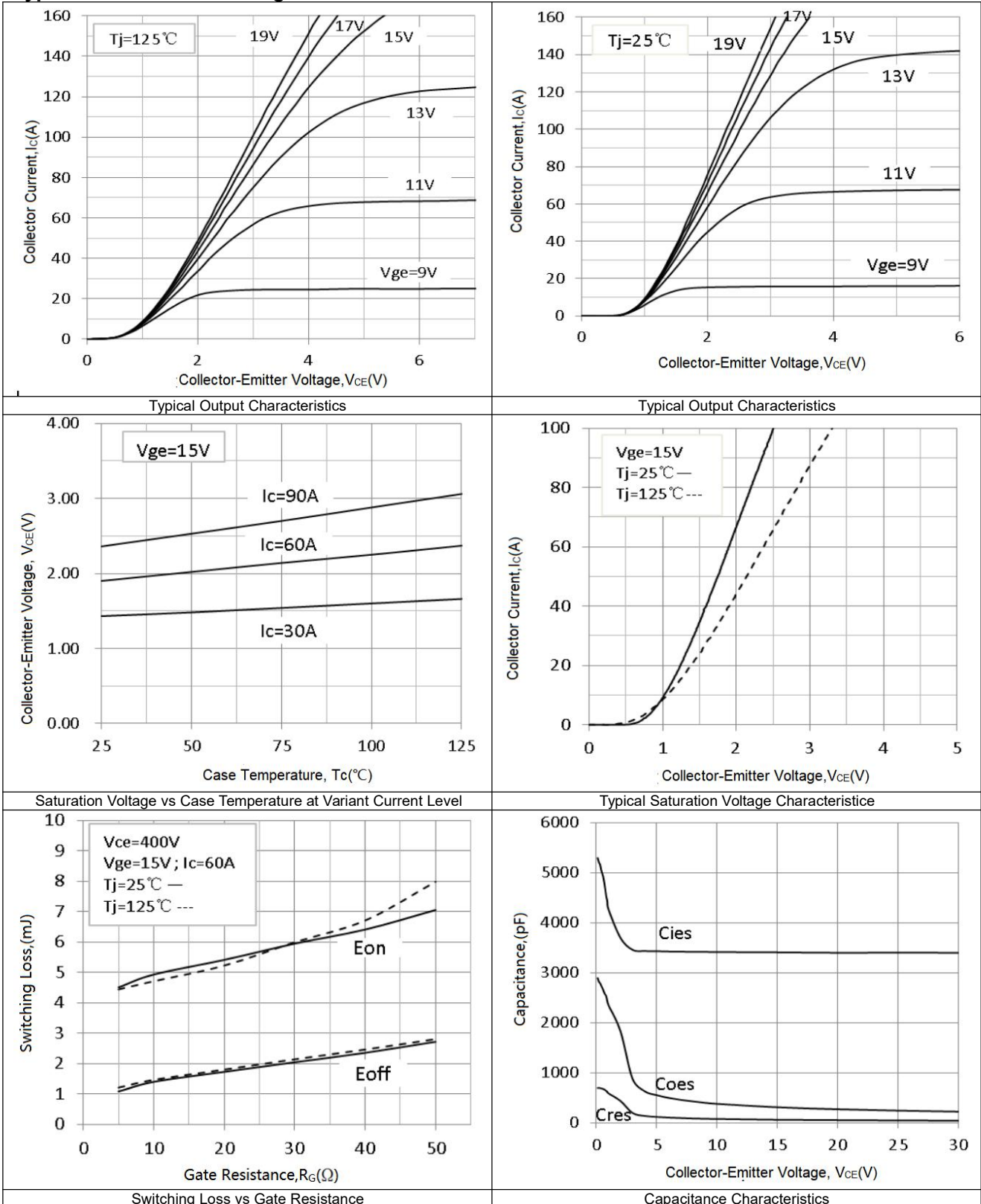
**Thermal Characteristics**

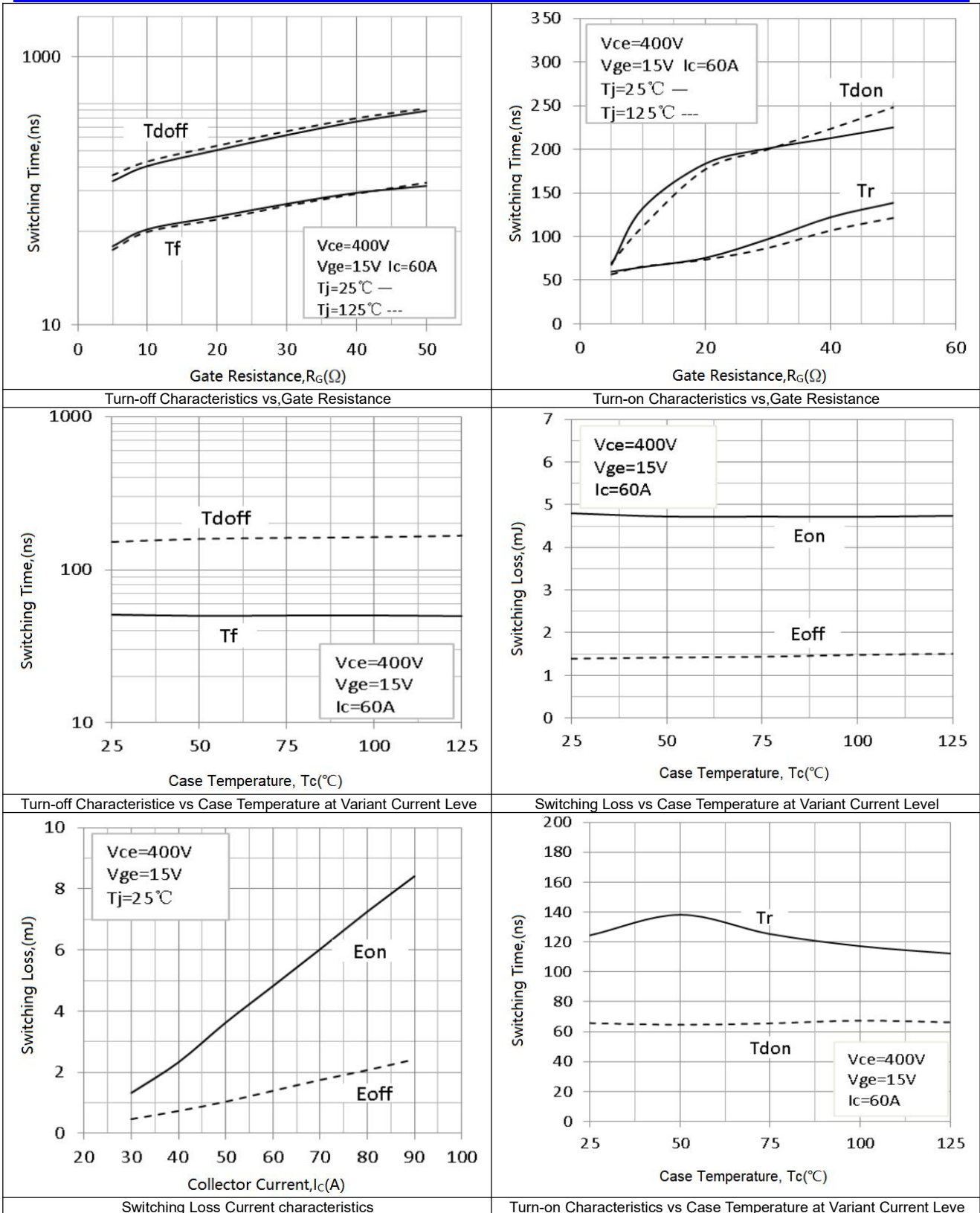
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta_{JC}}$	Thermal Resistance, Junction to case for IGBT	--	0.446	$^\circ C/W$
$R_{\theta_{JC}}$	Thermal Resistance, Junction to case for Diode	--	1.25	$^\circ C/W$
$R_{\theta_{JA}}$	Thermal Resistance, Junction to Ambient	--	40	$^\circ C/W$

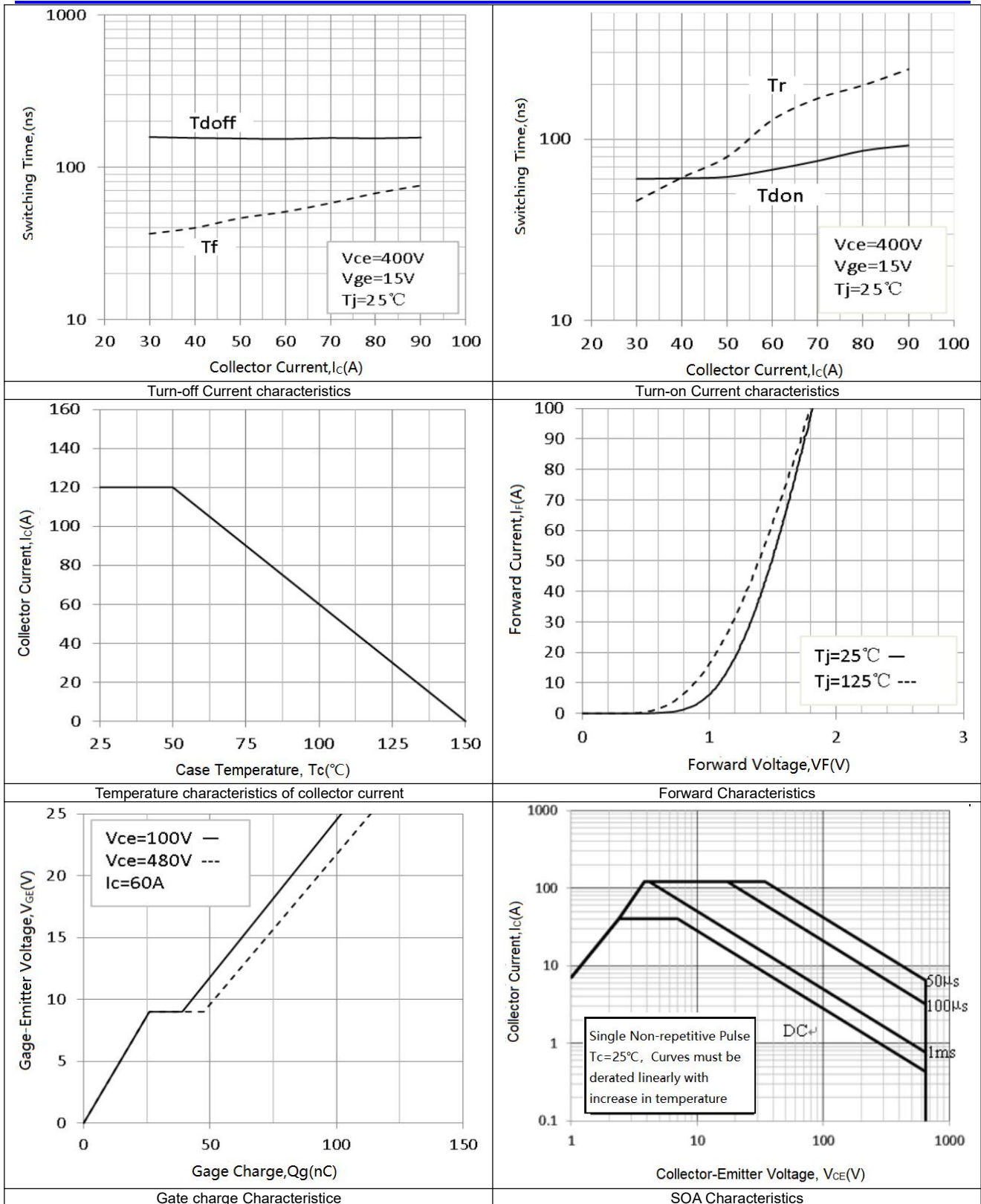
**Electrical Characteristics of the IGBT (Tc= 25°C unless otherwise specified) :**

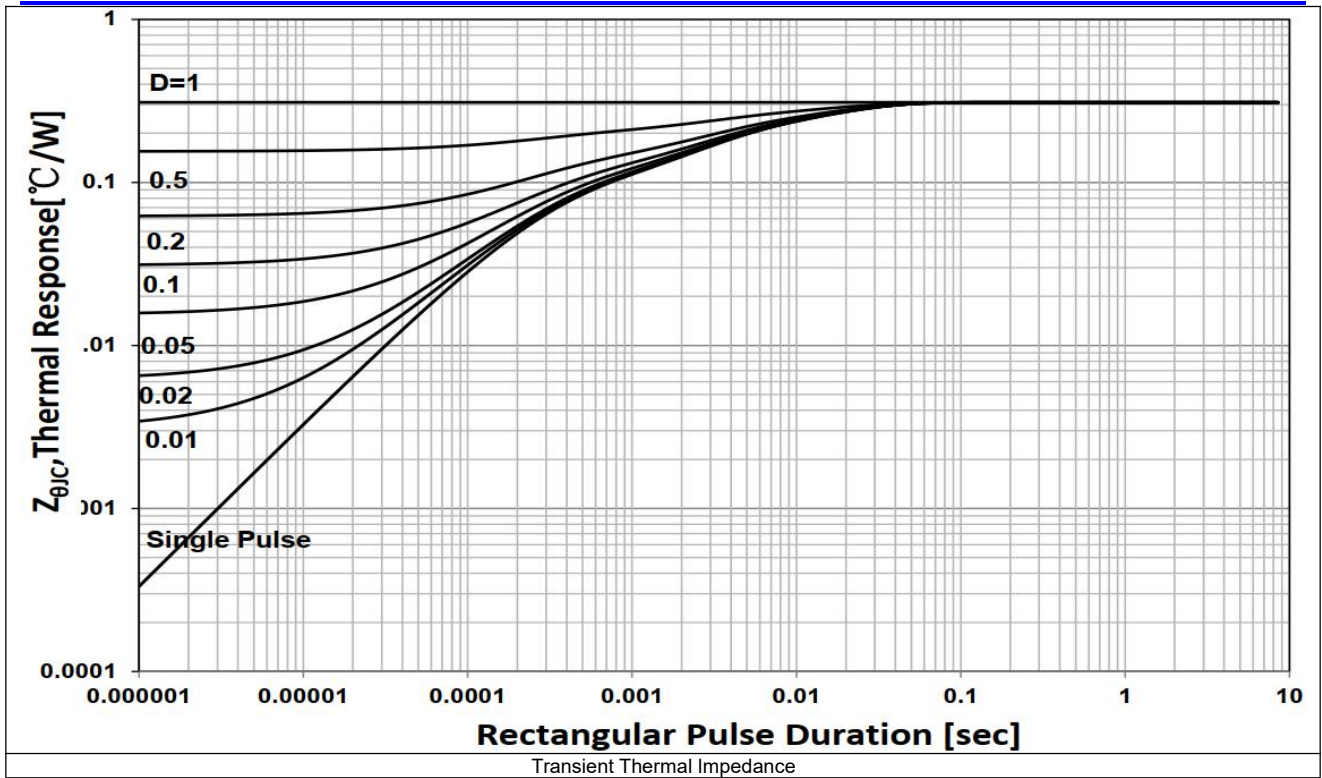
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
<b>OFF Characteristics</b>						
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_{CE}=250\mu A$	650	720	--	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0V, V_{CE}=650V$	--	--	3.0	mA
$I_{GES(F)}$	Gate to Emitter Forward Leakage	$V_{GE}=+20V$	--	--	+250	nA
$I_{GES(R)}$	Gate to Source Reverse Leakage	$V_{GE}=-20V$	--	--	-250	nA
<b>ON Characteristics</b>						
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=60A, V_{GE}=15V$	--	1.85	2.4	V
$V_{GE(th)}$	Gate Threshold Voltage	$I_C=1mA, V_{CE}=V_{GE}$	4.0	5.4	7.0	V
Pulse width $t_p \leq 300\mu s, \delta \leq 2\%$						
<b>Dynamic Characteristics</b>						
$C_{ies}$	Input Capacitance	$V_{CE}=30V, V_{GE}=0V$ $f=1MHz$	--	3398	--	pF
$C_{oes}$	Output Capacitance		--	224	--	
$C_{res}$	Reverse Transfer Capacitance		--	44	--	
<b>Resistive Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{CE}=400V, I_C=60A,$ $R_g=10\Omega, V_{GE}=15V,$ Inductive Load, $T_a=25^\circ C,$	--	66	--	ns
$t_r$	Rise Time		--	124	--	
$t_{d(off)}$	Turn-Off Delay Time		--	152	--	
$t_f$	Fall Time		--	51	--	
$E_{on}$	Turn-On Switching Loss	$V_{CE}=400V, I_C=60A,$ $R_g=10\Omega, V_{GE}=15V,$ Inductive Load, $T_a=25^\circ C,$	--	4.79	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	1.39	--	
$E_{ts}$	Total Switching Loss		--	6.18	--	
$t_{d(on)}$	Turn-on Delay Time	$V_{CE}=400V, I_C=60A,$ $R_g=10\Omega, V_{GE}=15V,$ Inductive Load, $T_a=25^\circ C,$	--	66	--	ns
$t_r$	Rise Time		--	112	--	
$T_{d(off)}$	Turn-Off Delay Time		--	167	--	
$t_f$	Fall Time		--	50	--	
$E_{on}^{a2}$	Turn-On Switching Loss	$V_{CE}=400V, I_C=60A,$ $V_{GE}=15V,$	--	4.73	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	1.50	--	
$E_{ts}$	Total Switching Loss		--	6.23	--	
$Q_g$	Total Gate Charge	$V_{CE}=400V, I_C=60A,$ $V_{GE}=15V,$	--	117	--	nC
$Q_{ge}$	Gate to Emitter Charge		--	35	--	
$Q_{gc}$	Gate to Collector Charge		--	47	--	
<b>Electrical Characteristics of the DIODE</b>						
$V_F$	Diode Forward Voltage	$I_F=30A$	--	1.3	1.8	V
$t_{rr}$	Reverse Recovery Time	$I_F=30A$ $di/dt=200A/\mu S$	--	80	--	ns
$I_{rrm}$	Diode Peak Reverse Recovery Current		--	6	--	A
$Q_{rr}$	Reverse Recovery Charge		--	240	--	nC
Pulse width $t_p \leq 300\mu s, \delta \leq 2\%$						

**Typical characteristics diagrams**



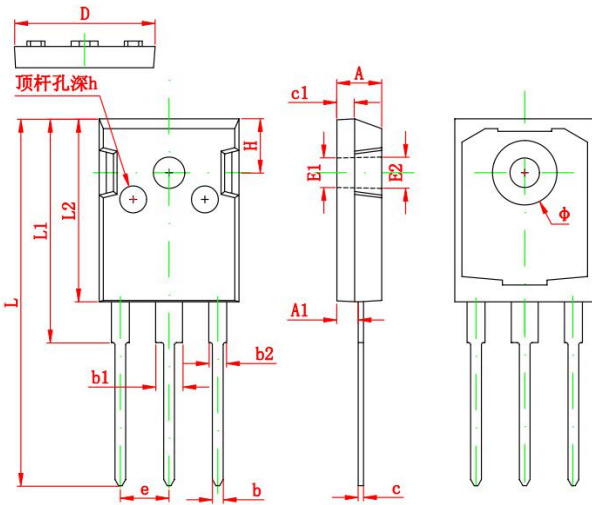






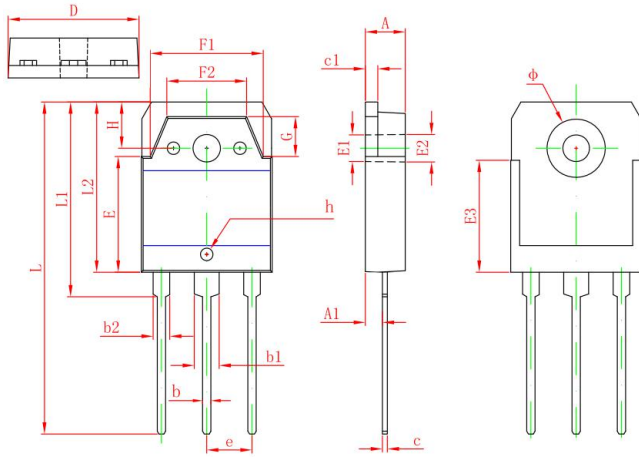
**Dimensions**

**TO-247 PACKAGE OUTLINE DIMENSIONS**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	
h	0.000	0.300	0.000	0.012

## TO-3PN PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.600	5.000	0.181	0.197
A1	2.200	2.600	0.087	0.102
b	0.800	1.200	0.031	0.047
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.450	1.650	0.057	0.065
D	15.450	15.850	0.608	0.624
E	13.700	14.100	0.539	0.555
E1	3.200 REF		0.126 REF	
E2	3.300 REF		0.130 REF	
E3	13.450 REF		0.530 REF	
F1	13.400	13.800	0.528	0.543
F2	9.400	9.800	0.370	0.386
L	39.900	40.300	1.571	1.587
L1	23.200	23.600	0.913	0.929
L2	20.300	20.600	0.799	0.811
φ	6.900	7.100	0.272	0.280
G	5.150	5.550	0.203	0.219
e	5.450 TYP		0.215 TYP	
H	5.000 REF		0.197 REF	
h	0.000	0.300	0.000	0.012